attaching a first end of a first bond wire to the bond pad of the first semiconductor wafer section and attaching a second end of the first bond wire to the kerf area;

attaching a first end of a second bond wire to the bond pad of the second semiconductor wafer section and attaching a second end of the second bond wire to the kerf area; ~~and~~

providing an encapsulation material over a major surface of the unsingularized wafer section to encapsulate the first and second bond wires;

subsequent to attaching the first and second bond wires, segmenting the first semiconductor wafer section from the second semiconductor wafer section; and

during the segmenting of the first semiconductor wafer section from the second semiconductor wafer section, exposing the first bond wire at a first surface of the encapsulation material and exposing the second bond wire at a second surface of the encapsulation material.

5. (canceled)

6. (original) The method of claim ~~5~~ 4 further comprising segmenting the first semiconductor wafer section from the second semiconductor wafer section using a saw which removes at least a portion of the kerf area, the first and second bond wires, and the encapsulation material.

7. (original) The method of claim ~~5~~ 4 further comprising segmenting the first semiconductor wafer section from the second semiconductor wafer section using an etching process which removes at least a portion of the kerf area, the first and second bond wires, and the encapsulation material.